# MSKSEMI 美森科













ESD

TVS

TSS

MOV

GDT

PLED

**BAT54WS** 

# **Product specification**





## FEATURES

- Extremely Fast Switching Speed
- Low Forward Voltage

## **Reference News**

PACKAGE OUTLINE	PIN CONFIGURATION	Marking
		L9
SOD-323		

## Maximum Ratings @Ta=25℃

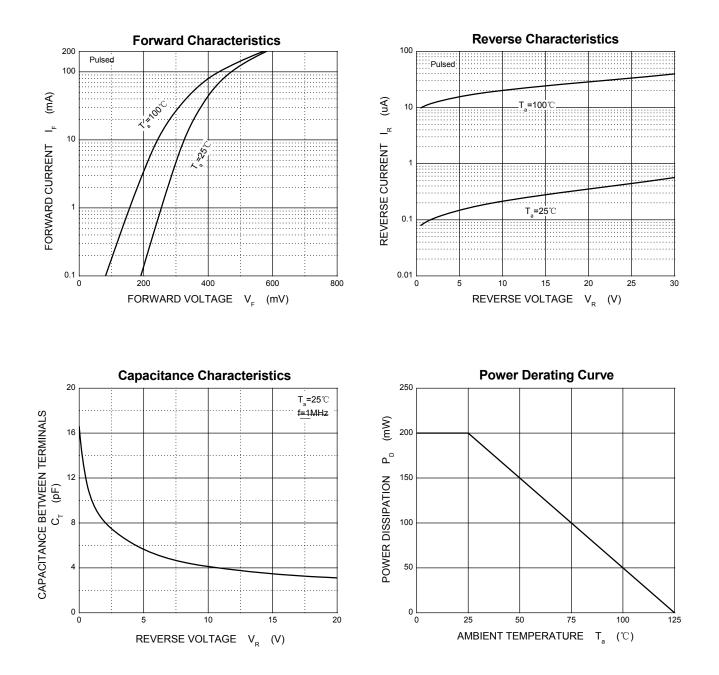
Parameter	Symbol	Limit	Unit
Non-Repetitive Peak Reverse Voltage	V <sub>RM</sub>	30	V
DC Blocking Voltage	VR	21	V
Average Rectified Output Current	lo	100	mA
Forward Continuous Current	lF	200	mA
Repetitive Peak Forward Current	IFRM	300	mA
Non-repetitive Peak Forward Surge Current @t=8.3ms	IFSM	600	mA
Power Dissipation	Po	200	mW
Thermal Resistance Junction to Ambient	R θJA	500	°C/W
Operating Junction Temperature Range	TJ	-40 ~ +125	°C
Storage Temperature Range	Tstg	-55 ~ +150	°C

## Electrical Characteristics @Ta=25°C

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Reverse breakdown voltage	V (BR)	l <sub>R</sub> =100µA	30			V
	V <sub>F1</sub>	l⊧=0.1mA			240	mV
	V <sub>F2</sub>	l⊧=1.0mA			320	mV
Forward voltage	V <sub>F3</sub>	l⊧=10mA			400	mV
	VF4	l⊧=30mA			500	mV
	V <sub>F5</sub>	l⊧=100mA			1000	mV
Reverse current	l <sub>R</sub>	V <sub>R</sub> =25V			2.0	uA
Reverse recovery time	trr	l⊧=10mA, l <sub>R</sub> =10mAto 1mA , R∟=100 Ω			5.0	ns
Capacitance between terminals	Ст	V <sub>R</sub> =1V,f=1MHz			10	pF

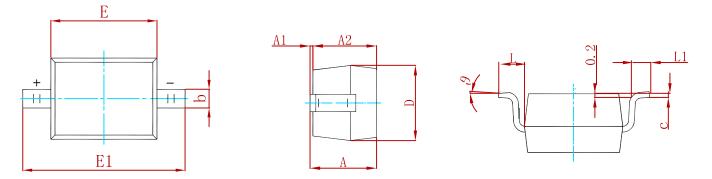


# BAT54WS



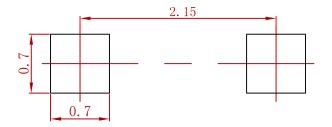


#### PACKAGE MECHANICAL DATA



Cymra a l	Dimensions In Millimeters		Dimensions In Inches		
Symbol	Min.	Max.	Min.	Max.	
A		1.000		0.039	
A 1	0.000	0.100	0.000	0.004	
A2	0.800	0.900	0.031	0.035	
b	0.250	0.350	0.010	0.014	
с	0.080	0.150	0.003	0.006	
D	1.200	1.400	0.047	0.055	
ш	1.600	1.800	0.063	0.071	
E1	2.550	2.750	0.100	0.108	
Ľ	0.475 REF.		0.019 REF.		
L1	0.250	0.400	0.010	0.016	
θ	0°	8°	0°	8°	

#### **Suggested Pad Layout**



Note: 1.Controlling dimension:in millimeters.

2.General tolerance:±0.05mm.
3.The pad layout is for reference purposes only.

## **REEL SPECIFICATION**

P/N	PKG	QTY
BAT54WS	SOD-323	3000



### **Attention**

■ Any and all MSKSEMI Semiconductor products described or contained herein do not have specifications that can handle applications that require extremely high levels of reliability, such as life-support systems, aircraft's control systems, or other applications whose failure can be reasonably expected to result in serious physical and/or material damage. Consult with your MSKSEMI Semiconductor representative nearest you before using any MSKSEMI Semiconductor products described or contained herein in such applications.

MSKSEMI Semiconductor assumes no responsibility for equipment failures that result from using products at values that exceed, even momentarily, rated values (such as maximum ratings, operating condition ranges, or other parameters) listed in products specifications of any and all MSKSEMI Semiconductor products described or contained herein.

Specifications of any and all MSKSEMI Semiconductor products described or contained herein stipulate the performance, characteristics, and functions of the described products in the independent state, and are not guarantees of the performance, characteristics, and functions of the described products as mounted in the customer's products or equipment. To verify symptoms and states that cannot be evaluated in an independent device, the customer should always evaluate and test devices mounted in the customer's products or equipment.

MSKSEMI Semiconductor. strives to supply high-quality high-reliability products. However, any and all semiconductor products fail with someprobability. It is possible that these probabilistic failures could give rise to accidents or events that could endanger human lives, that could give rise to smoke or fire, or that could cause damage to other property. When designing equipment, adopt safety measures so that these kinds of accidents or events cannot occur. Such measures include but are not limited to protective circuits anderror prevention circuits for safedesign, redundant design, and structural design.

■ In the event that any or all MSKSEMI Semiconductor products (including technical data, services) described or contained herein are controlled under any of applicable local export control laws and regulations, such products must not be exported without obtaining the export license from theauthorities concerned in accordance with the above law.

■ No part of this publication may be reproduced or transmitted in any form or by any means, electronic or

mechanical, including photocopying and recording, or any information storage or retrieval system, or otherwise, without the prior written permission of MSKSEMI Semiconductor.

Information (including circuit diagrams and circuit parameters) herein is for example only ; it is not guaranteed for volume production. MSKSEMI Semiconductor believes information herein is accurate and reliable, but no guarantees are made or implied regarding its use or any infringements intellectual property rights or other rights of third parties.

Any and all information described or contained herein are subject to change without notice due to

product/technology improvement, etc. Whendesigning equipment, referto the "Delivery Specification" for the MSKSEMI Semiconductor productthat you intend to use.

单击下面可查看定价,库存,交付和生命周期等信息

>>MSKSEMI (美森科)